

## Oxygen vacancy-dependent density-of-states and its effect on the negative bias illumination stress-induced degradation in amorphous oxide semiconductor thin-film transistors

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Negative bias illumination stress (NBIS)-induced instability have emerged as a challenging issue for mass production of the display backplanes using amorphous oxide semiconductor (AOS) thin-film transistors (TFTs) [1]. On the other hand, oxygen vacancy ( $V_O$ ) has been well known as critical material/process-controlled parameter for AOS technology [2]. However, details for the effect of the amount of  $V_O$ s on the density of subgap states (DOS) experimentally extracted from TFT characteristics have been rarely addressed. Here we report the  $V_O$ -dependent DOS and its effect on NBIS degradation in amorphous InGaZnO (a-IGZO) TFTs [Fig.1 (a)]. The amount of  $V_O$ s was controlled by changing the oxygen flow rate (OFR) of the dc sputtering with a gas mixture of Ar/ $O_2$  (35/OFR sccm) from 21, 42 to 63. DOS was extracted by the monochromatic photonic capacitance-voltage technique [3]. It was found that the OFR-controlled amount of  $V_O$ s changed the DOS near valence band edge as well as that the DOS near conduction band edge [Fig. 1(c)], which explained well the OFR-dependent I-V/mobility curve [Fig. 1(b)] and NBIS degradation [Fig. 1(d)]. Noticeably, the OFR-sensitive DOS peak was found to be located around in 1 eV above valence band edge, which was consistent with [4]. Physical mechanism and details on methods will be presented. Our results are expected as great promise in not only the physical insight on the  $V_O$ -effect on the trade-off between the performance and instability but also the method for optimizing the amount of  $V_O$ s in AOS TFT technology.

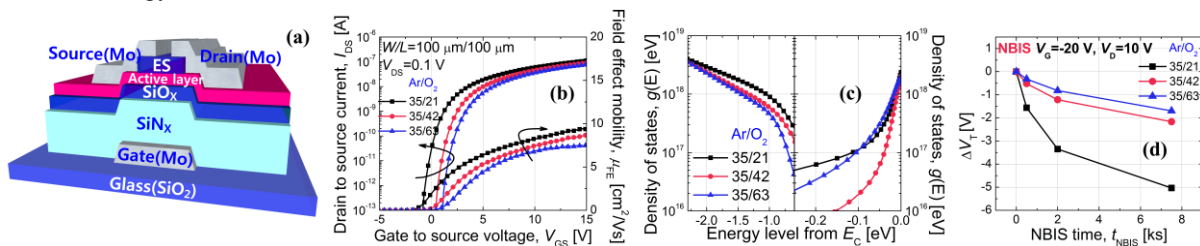


Fig. 4. (a) a-IGZO TFTs device structure, (b) the  $I_{DS}$ - $V_{GS}$  transfer curve and field-effect mobility, (c) extracted the subgap DOS, (d) and the NBIS-induced  $\Delta V_T$  as a function of stress time.

[1] Y. Kim et al., IEEE Trans. Electron Devices, 59, pp. 2699-2706 (2012).

[2] S. Kim et al., IEEE Electron Devices Letters, 33, pp. 62-64 (2012).

[3] H. Bae et al., SID Symposium Digest of Technical Papers, 44, pp. 1033-1036 (2013).

[4] S. Lee et al., IEEE IEDM Technical Digest, pp. 24.3.1-24.3.4 (2012).